TOSHIBA Field Effect Transistor Silicon N Channel MOS Type

SSM3K316T

Power Management Switch Applications High-Speed Switching Applications

• 1.8-V drive

• Low ON-resistance: $R_{on} = 131 \text{ m}\Omega \text{ (max) (@V_{GS} = 1.8 V)}$

 $R_{on} = 87 \text{ m}\Omega \text{ (max) (@V}_{GS} = 2.5 \text{ V)}$ $R_{on} = 65 \text{ m}\Omega \text{ (max) (@V}_{GS} = 4.5 \text{ V)}$ $R_{on} = 53 \text{ m}\Omega \text{ (max) (@V}_{GS} = 10 \text{ V)}$

Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol		Rating	Unit	
Drain-source voltage		V_{DSS}		30	V	
Gate-source voltage		V_{GSS}		± 12	٧	
Drain current	DC	ID	(Note 1)	4.0	Α	
	Pulse	I _{DP}	(Note 1)	8.0	τ.	
Drain power dissipation		PD	(Note 2)	700	mW	
			t = 10s	1250	IIIVV	
Channel temperature		T _{ch}		150	°C	
Storage temperature range		T _{stg}		-55 to 150	°C	

Note:

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: The Junction temperature should not exceed 150°C during use.

Note 2: Mounted on an FR4 board. (25.4 mm \times 25.4 mm \times 1.6 mm, Cu Pad: 645 mm²)

1. GATE 2. SOURCE 3. DRAIN TSM JEDEC JEITA TOSHIBA 2.8**023 1.6**021 200099170 20

Weight: 10 mg (typ.)

Electrical Characteristics (Ta = 25°C)

Charact	eristics	Symbol	Test Condition	Min	Тур.	Max	Unit	
Drain-source breakdown voltage	V (BR) DSS	$I_D = 1 \text{ mA}, V_{GS} = 0 \text{ V}$		30	_		V	
Diaiii–source breakdowii voltage		V (BR) DSX	$I_D = 1 \text{ mA}, V_{GS} = -12 \text{ V}$		18			V
Drain cutoff curren	t	I _{DSS}	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$				1	μΑ
Gate leakage curre	ent	I _{GSS}	$V_{GS} = \pm 12 \text{ V}, V_{DS} = 0 \text{ V}$				±1	μА
Gate threshold vol	tage	V _{th}	$V_{DS} = 3 \text{ V}, I_{D} = 1 \text{ mA}$		0.4		1.0	V
Forward transfer a	dmittance	Y _{fs}	$V_{DS} = 3 V, I_{D} = 2 A$	(Note3)	3.8	7.7		S
		R _{DS} (ON)	$I_D = 3.0 \text{ A}, V_{GS} = 10 \text{V}$	(Note3)		42	53	· mΩ
Drain-source ON-resistance	$I_D = 2.0 \text{ A}, V_{GS} = 4.5 \text{ V}$		(Note3)		51	65		
Diain-source On-resistance			$I_D = 1.0 \text{ A}, V_{GS} = 2.5 \text{ V}$	(Note3)		64	87	
			$I_D = 0.5 \text{ A}, V_{GS} = 1.8 \text{ V}$	(Note3)	_	81	131	
Input capacitance		C _{iss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz			270		pF
Output capacitance		Coss				56		
Reverse transfer capacitance		C _{rss}				47		
Total Gate Charge Gate-Source Charge		Qg	V _{DS} = 15 V, I _{DS} = 3.0 A V _{GS} = 4 V		_	4.3	_	nC
		Q _{gs}				2.8	_	
Gate-Drain Charge		Q _{gd}			_	1.5	_	
Switching time	Turn-on time	t _{on}	$V_{DD} = 10 \text{ V}, I_D = 2 \text{ A},$ $V_{GS} = 0 \text{ to } 2.5 \text{ V}, R_G = 4.7 \Omega$		_	20	_	ns
	Turn-off time	t _{off}				31		
Drain-source forward voltage		V _{DSF}	$I_D = -4.0 \text{ A}, V_{GS} = 0 \text{ V}$	(Note3)		- 0.9	- 1.2	V

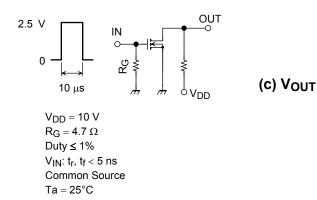
Note3: Pulse test

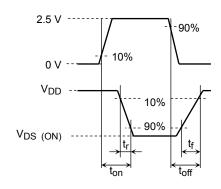
Start of commercial production 2008-04

Switching Time Test Circuit

(a) Test Circuit

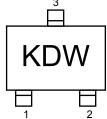
(b) V_{IN}



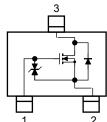


Marking





Equivalent Circuit (top view)



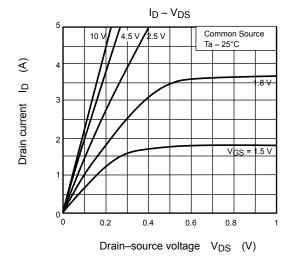
Usage Considerations

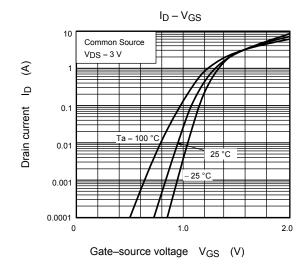
Let V_{th} be the voltage applied between gate and source that causes the drain current (I_D) to below 1 mA for the SSM3K316T). Then, for normal switching operation, $V_{GS(on)}$ must be higher than V_{th} , and $V_{GS(off)}$ must be lower than V_{th} . This relationship can be expressed as: $V_{GS(off)} < V_{th} < V_{GS(on)}$.

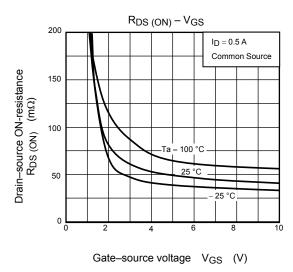
Take this into consideration when using the device.

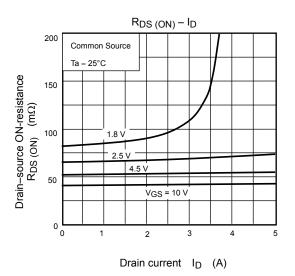
Handling Precaution

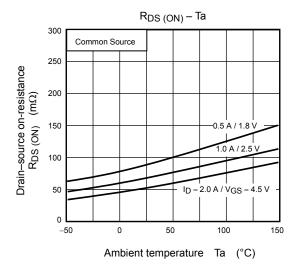
When handling individual devices that are not yet mounted on a circuit board, make sure that the environment is protected against electrostatic discharge. Operators should wear antistatic clothing, and containers and other objects that come into direct contact with devices should be made of antistatic materials.

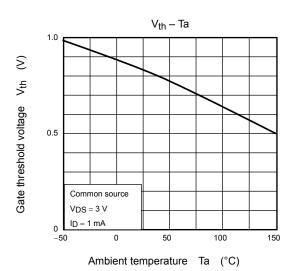


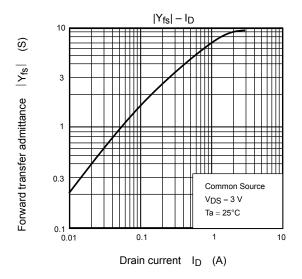


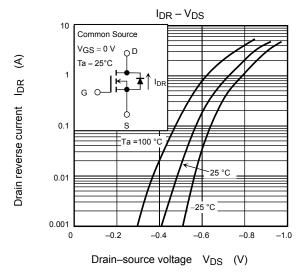


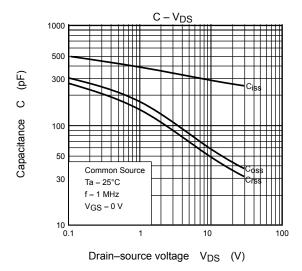


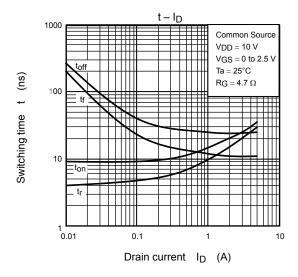


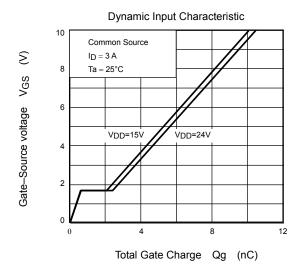




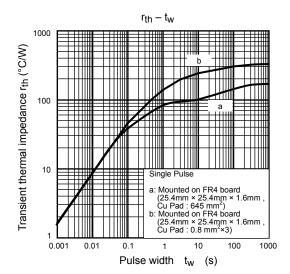


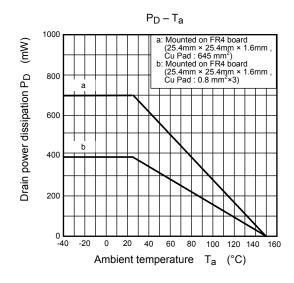






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